



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPD70R2K0CE	Issued	25. June 2021
MA#	MA005558444		
Package	PG-TO252-3-344	Weight*	322.10 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.525	0.47	0.47	4734	4734
leadframe	inorganic material	phosphorus	7723-14-0	0.053	0.02		165	
	non noble metal	iron	7439-89-6	0.177	0.06		550	
	non noble metal	copper	7440-50-8	176.899	54.93	55.01	549199	549914
wire	non noble metal	aluminium	7429-90-5	0.588	0.18	0.18	1826	1826
encapsulation	organic material	carbon black	1333-86-4	0.686	0.21		2129	
	plastics	epoxy resin	-	18.518	5.75		57492	
	inorganic material	silicondioxide	60676-86-0	117.969	36.62	42.58	366247	425868
leadfinish	non noble metal	tin	7440-31-5	3.834	1.19	1.19	11901	11901
solder	non noble metal	tin	7440-31-5	0.037	0.01		115	
	noble metal	silver	7440-22-4	0.046	0.01		144	
	non noble metal	lead	7439-92-1	1.771	0.55	0.57	5498	5757
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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